

规格书编号

SPEC NO: HDR433MS8SP04

产品规格书 SPECIFICATION

CUSTOMER 客 户:_____

| PRODUCT 产品: | SAW RESONATOR | | | |
|-------------------------|---------------|--------------|--|--|
| MODEL NO 型 号: | HDR433M-S8 | | | |
| PREPARED 编 制: | CHECKED 审 核 | 亥: | | |
| APPROVED 批准: | DATE 日 | 月:2016-11-23 | | |
| 客户确认 CUSTOMER RECEIVED: | | | | |
| 审核 CHECKED | 批准 APPROVED | 日期 DATE | | |
| | | | | |

无锡市好达电子有限公司 Shoulder Electronics Limited



更改历史记录 History Record

| 更改日期 Date | 规格书编号 Spec. No. | 产品型号 Part No. | 客户产品型号 Customer No. | 更改内容描述 Modify Content | 备注 Remark |
|--------------|--------------------|------------------|------------------------|--|--------------|
| 2016-01-11 | SP02 | HDR433M-P 8 | | Insertion Loss | |
| 2016-05-09 | SP03 | HDR433M-P 8 | | Modify the Carrier Tape Dimensions. | |
| 2016-11-23 | SP04 | HDR433M-P 8 | | Change pin no., lack of foot is no. 1. Do not change the size, the use. | |
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1. Scope

This specification shall cover the characteristics of 1-port SAW resonator with R433M used for remote-control security.

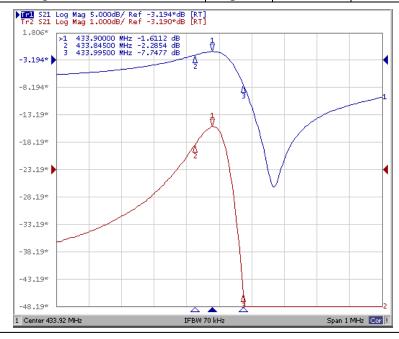
2. Electrical Specification

2.1 Maximum Rating

| DC Voltage VDC | 10V |
|-----------------------|----------------|
| AC Voltage Vpp | 10V 50Hz/60Hz |
| Operation temperature | -40°C to +85°C |
| Storage temperature | -45°C to +85°C |
| Max Input Power | 10dBm |

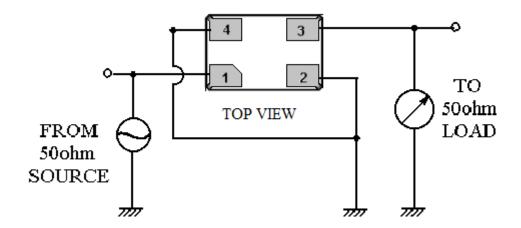
2.2 Electronic Characteristics

| Item | | Unites | Minimum | Typical | Maximum | |
|----------------------------------|-------------------------|----------------|--------------|---------|---------|----|
| Center Frequency | | MHz | 433.845 | 433.920 | 433.995 | |
| Insertion Loss | | dB | | 1.8 | 2.2 | |
| Onelity Factor Unload Q | | Unload Q | | 8300 | 12000 | |
| Quality Facto | ľ | 50Ω Loaded Q | | 850 | 1500 | |
| Temperature | Turnov | er Temperature | $^{\circ}$ C | 10 | 25 | 40 |
| Stability | Freq.ter | mp.Coefficient | ppm/℃ | | 0.032 | |
| Frequency Aging | | ppm/yr | | <±10 | | |
| DC. Insulation | n Resista | nce | ΜΩ | 1.0 | | |
| RF | Motional Resistance R1 | | Ω | | 18 | 26 |
| Equivalent | Motional Inductance L1 | | μН | | 79.82 | |
| RLC Model | Motional Capacitance C1 | | fF | | 1.685 | |
| Transducer Static Capacitance C0 | | pF | | 2.3 | | |

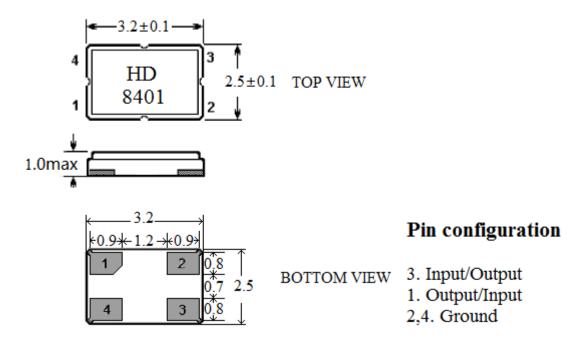




3. TEST CIRCUIT



4. DIMENSION



5. Environment Characteristic

5-1 High temperature exposure

Subject the device to $+85^{\circ}$ C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

5-2 Low temperature exposure

Subject the device to -40° C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+85^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2-2.



HDR433M-S8

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260° C $\pm 10^{\circ}$ C for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2-2.

5-5 Solderability

Subject the device terminals into the solder bath at 245° C $\pm 5^{\circ}$ C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2-2.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2-2.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2-2.

6. Remark

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

7. Packing

7.1 Dimensions

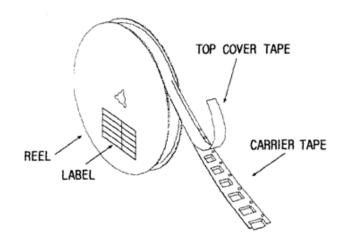
- (1) Carrier Tape: Figure 1
- (2) Reel: Figure 2
- (3) The product shall be packed properly not to be damaged during transportation and storage.

7.2 Reeling Quantity

1000 pcs/reel 7"

7.3 Taping Structure

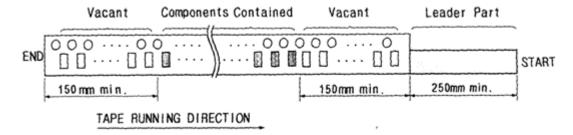
(1) The tape shall be wound around the reel in the direction shown below.



(2) Label

| Device Name | |
|-------------------|--|
| User Product Name | |
| Quantity | |
| Lot No. | |

(3) Leader part and vacant position specifications.

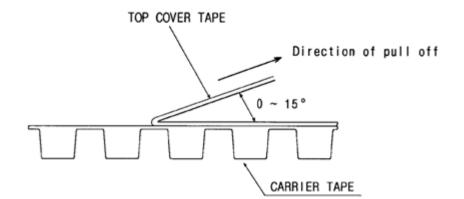


8. TAPE SPECIFICATIONS

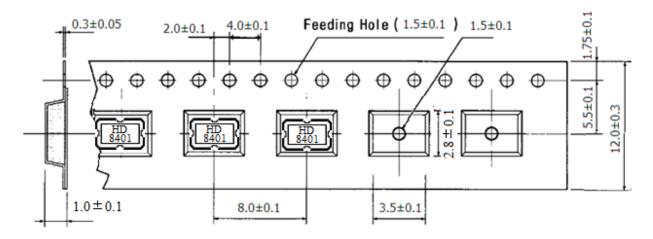
8.1 Tensile Strength of Carrier Tape: 4.4N/mm width

8.2 Top Cover Tape Adhesion (See the below figure)

(1) pull off angle: 0~15°
(2) speed: 300mm/min.
(3) force: 20~70g

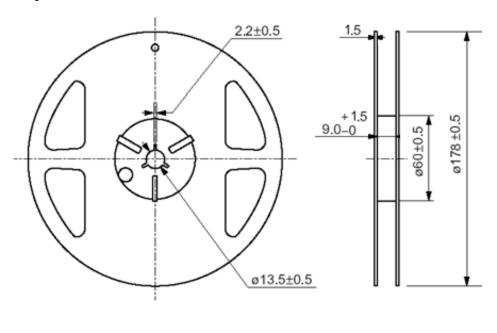


[Figure 1] Carrier Tape Dimensions



Tape Running Direction

[Figure 2] 1000 pcs/reel



ø178 Reel Dimension

(in mm)